朝貴電子股份有限公司
CKM ELECTRONICS CO., LTD.

PRODUCT SPECIFICATION

WIRE TO BOARD 1.00 MM PITCH

CKM PN: A1004 SERIES

REVISION HISTORY:

REV	REVISION DESCRIPTION	DATE	CREATED/REVISED
1	INTERIM EDITION	2014/4/26	Rock
2	UPGRADE ITEM 9.5	2014/11/06	Rock
A	UPGRADE ITEM 7.3	2022/05/31	Rock

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1.0 SCOPE

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire.

2.0 APPLICABLE STANDARDS

MIL - STD - 202 Methods for test of connectors for electronic equipment
MIL - STD - 1344 Test methods for electrical connectors
JIS C0020, C0021, C0025
JIS C5028
JIS C5402
UL 1977

3.0 APPLICABLE SERIES NO: A1004 SMT TYPE SERIES

Header P/N: A1004WR-XX-XX-HF-X
Housing P/N: A1004HV-XX-A-HF
Terminal P/N: A1004T0X-X

4.0 PRODUCT SHAPE, DIMENSIONS AND MATERIALS

*See attached drawings.

5.0 MATERIALS

*See attached drawings.

6. ACCOMMODATED P.C. BOARD

6.1 Thickness: 0.6 mm (.024 ")～1.2mm (.047 "), 1.6 mm (.063 ")
6.2 P.C. Board Layout: See attached drawings

7. RATINGS

7.1 Current rating: 1.0A AC, DC (AWG #28)

7.2 Voltage rating: 125V AC, DC

7.3 Temperature range:-40℃ to +105℃

7.4 Applicable wire: AWG #32 to #28, Insulation O.D.: 0.65~0.92mm Max.

8. PERFORMANCE REQUIREMENTS AND TEST DESCRIPTIONS

The product is designed to meet the electrical, mechanical and environmental performance Requirements as specifics in **9.0 REQUIREMENTS.**

9.0 TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST ITEM		REQUIREMENT	PROCEDURE
9.1	Examination of Product	Meets requirements of product drawing. No physical damage.	Per **EIA-364-18** Visual inspection
ELECTRICAL REQUIREMENT			
9.2	Contact Resistance	20mΩ Max (Initial) 40mΩ Max (Final)	Dry circuit of DC 20 mV max. , 100 mA max.(JIS C5402 5.4)
9.3	Insulation Resistance	100MΩ Min	When applied DC 500 V between adjacent terminal or ground (JIS C5402 5.2/MIL-STD 202 method 301)
9.4	Dielectric Withstanding Voltage	No change.	When applied AC 500 V 1 minute between adjacent terminal (JIS C5402 5.2/MIL-STD 202 method 302 Cond. B)
MECHANICAL REQUIREMENT			
9.5	Terminal crimp Tensile strength	AWG # 28: 1.3kgf Min. AWG # 30: 0.8kgf Min. AWG # 32: 0.6kgf Min.	Fix the crimped terminal, apply axial pull out force on the wire at speed rate of 25±3 mm/minute. *Crimping specification refer to Figure 2
9.6	Terminal / Housing Retention Force (For Plug)	0.6kgf Min.	Retention speed 25±3 mm per minute from housing
9.7	Mating & Un-mating force	See Item 12	Insert and withdraw connector at speed of 25 ±3 mm per minute

9.8	Durability	Contact resistance: Less than twice of initial Dielectric Withstanding Voltage: To pass Para 9.4	Connector shall be subjected to 30 cycles of insertion and withdrawal (repeatedly by the rate of 10 cycles per minute)
9.9	Pin retention force (For Header)	0.4kgf Min.	Push pin from insulator base at speed 25± 3 mm per minute
9.10	Locking force	3kgf Min.	While withdrawing plug & receptacle without terminal at speed 25±3 mm per minute
ENVIRONMENTAL REQUIREMENTS			
9.11	Temperature rise	30°C max.	Then carried the rated current (UL 1977)
9.12	Vibration	Appearance: No damage Discontinuity: 1 micro second max.	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions (MIL-STD-202,method 201A)
9.13	Heat aging	No damage Contact resistance: Less than twice of initial	105 ± 2°C , 96 hours(JIS C0021/MIL-STD-202,method 108A,condition A)
9.14	Humidity	Appearance: No damage Contact resistance: Less than twice of initial Insulation resistance: To pass Para 9.3	60 ± 2°C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested (JIS C0020/MIL-STD-202, method 103 B, condition B)
9.15	Temperature cycling	Appearance: No damage Contact resistance: Less than twice of initial	Five cycle consists of :(JIS C0025) (1)-55 °C+0/-03°C , 30 min. (2)Room temp. 10-15 min. (3) 85 °C+3/-0°C , 30 min. (4)Room temp. 10-15 min.

9.16	Salt spray	Appearance: No damage Contact resistance: Less than twice of initial	Temperature: 35 ± 2°C Solution: 5 ± 1% Spray time: 48±4 hours Measurement must be taken after water rinse(JIS C5028/MIL-STD-202, method 101 D, condition B)
9.17	Solder ability	Minimum: 90% of immersed area	Lead-Free Process for SMT Type: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C
9.18	Resistance to IR reflow heat (SMT)	No damage	Refer Reflow temperature profile
9.19	Resistance to soldering heat	No damage	Apply solder iron in solder tail Temperature: 350±10℃, 3~4 sec.

10. RECOMMENDED IR REFLOW TEMPERATURE PROFILE

10.1 Using Lead-Free Solder Paste

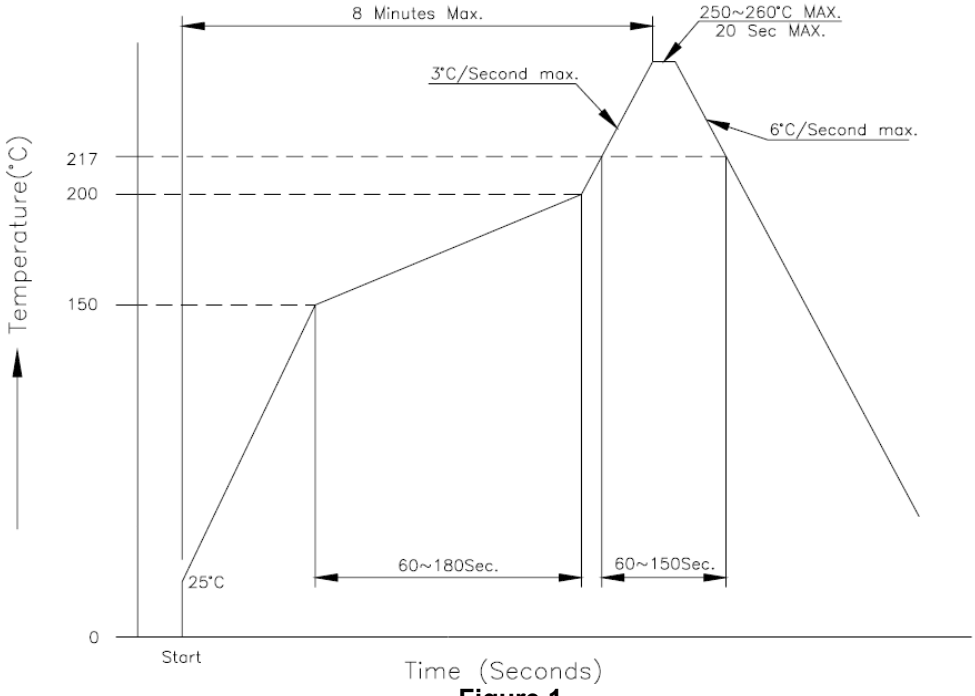

Figure 1

11. CRIMPING SPECIFICATION

A1004T0X-X				
Wire Size (AWG)		#28	#30	#32
1. CONDUCTOR (mm)	CRIMP WIDTH	0.65±0.05		
	CRIMP HEIGHT	0.55~0.63	0.50~0.58	0.45~0.53
2. INSULATION (mm)	CRIMP WIDTH	0.7±0.05		
	CRIMP HEIGHT	0.90	0.80	0.70
CRIMP STRENGTH		1.3Kgf (MIN)	0.8Kgf (MIN)	0.6Kgf (MIN)

Figure 2

12. MATING AND UN-MATING FORCE (REMOVE LATCH) :

PIN No.	At Initial		At 30th
	Mating (kgf Max.)	Un-mating (kgf Min.)	Un-mating (kgf Min.)
2	2.00	0.20	0.20
3	2.00	0.20	0.20
4	2.00	0.20	0.20
5	3.00	0.30	0.30
6	3.00	0.30	0.30
7	3.00	0.30	0.30
8	4.00	0.40	0.40
9	4.00	0.40	0.40
10	4.00	0.40	0.40
11	5.00	0.50	0.50
12	5.00	0.50	0.50
13	5.00	0.50	0.50
14	6.00	0.60	0.60
15	6.00	0.60	0.60
16	6.00	0.60	0.60
17	7.00	0.70	0.70
18	7.00	0.70	0.70
19	7.00	0.70	0.70
20	8.00	0.80	0.80

13. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

Test or Examination	Test Group										
	A	B	C	D	E	F	G	H	I	J	K
	Test Sequence (a)										
Examination of Product	1,8	1,7	1	1	1,3	1	1,5	1,5	1,4	1,3	1,3
Contact Resistance	2,7	2,6					2,4	2,4	2,3		
Insulation Resitance		3,5									
Dielectric withstanding Voltage	3,6										
Terminal crimp Tensile strength			2								
Terminal / Housing Insertion Force (For Plug)				2							
Mating & Un-mating force	4										
Durability	5										
Temperature Rise						2					
Vibration					2						
Heat aging							3				
Humidity		4									
Temperature cycling								3			
Salt spray									3		
Solder ability										2	
Resistance to IR reflow heat (SMT)											2
Sample Size	5	5	5	5	5	5	5	5	5	5	5